#### MAX20330

# Programmable OVP Controller with VBUS Short Detection

#### **General Description**

The MAX20330 is an overvoltage controller with the VBUS impedance detection function. The device drives an external low  $R_{ON}$  path for the device that requires a flexible and adjustable OVLO threshold. The VBUS impedance detection can detect the soft short on VBUS and warn the user about the potential connector overheating.

The MAX20330 is designed to drive a single or dual back-to-back external N-channel MOSFET with a low  $R_{ON}$  (10m $\Omega$  max). An external TVS can be used to protect the device from a high energy surge if necessary.

The device is available in an 8-bump (0.35mm pitch, 1.77mm x 1.03mm) wafer-level package (WLP) and operate over the -40°C to +85°C extended temperature range.

### **Applications**

- Smart Phones
- Tablets
- Phablets
- Desktops

#### **Benefits and Features**

- Protects High-Power Portable Devices
  - Wide Operating Input Voltage Protection Range: 2.7V to 36V
  - Ultra-Fast Turn-Off Time: 100nsec
  - · Built-In Charge Pump to Drive External N-MOSFET
- Flexible Overvoltage Protection Design
  - I<sup>2</sup>C Adjustable Overvoltage Protection Trip Level
  - Wide Adjustable OVLO Threshold Range from 4V to 24V (168 steps)
  - Preset Internal Accurate OVLO Thresholds: 6.8V±2%
- Additional Protection Features Increase System Reliability
  - · VBUS Short Detection
  - · Soft-Start to Minimize In-Rush Current
  - · Internal 15ms Startup Debounce
  - · Thermal Shutdown Protection
- Space-Saving
  - 8 Bump 0.35mm Pitch 1.77mm x 1.03mm WLP

Ordering Information appears at end of data sheet.



### **Absolute Maximum Ratings**

(All voltages referenced to GND.)	Continuous Power Dissipation (T <sub>A</sub> = +70°C)
VBUS to GND (Note 1)0.3V to +40V	WLP (derate 10.9mW/°C above +70°C)872mW
GATE to GND0.3V to min (VBUS + 0.3V, 40V)	Operating Temperature Range40°C to +85°C
OUT to GND0.3V to min (GATE + 0.3V, 40V)	Junction Temperature+150°C
GATE to OUT0.3V to +6V	Storage Temperature Range65°C to +150°C
SDA, SCL, INT, V <sub>CC</sub> to GND0.3V to +6V	Soldering Temperature (reflow)+260°C
Continuous Current into all pins±0.1A	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 1: The external TVS clamp voltage should be below the abs max of MAX20330.

### **Package Information**

PACKAGE TYPE: 8 WLP	
Package Code	W81B1+1
Outline Number	21-100229
Land Pattern Number	Refer to Application Note 1891
THERMAL RESISTANCE, FOUR-LAYER BOARD	
Junction to Ambient (θ <sub>JA</sub> )	91.72°C/W

For the latest package outline information and land patterns (footprints), go to <a href="www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <a href="https://www.maximintegrated.com/thermal-tutorial">www.maximintegrated.com/thermal-tutorial</a>.

#### **Electrical Characteristics**

(V<sub>BUS</sub> = 2.7V to 36V, V<sub>CC</sub> = 2.6V to 5.5V,  $T_A$  = -40°C to +85°C, unless otherwise noted. Typical values are at V<sub>CC</sub> = 3.3V,  $T_A$  = +25°C) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
VBUS						
VBUS Startup Voltage	V <sub>BUS_ST</sub>			2.7	2.75	V
VBUS Supply Current	I <sub>VBUS</sub>	$V_{BUS} = 4.2V$ , $I_{OUT} = 0mA$		250	400	μA
VBUS Pull Down Resistor	R <sub>PD</sub>	Enabled by I <sup>2</sup> C	0.5	1	2	kΩ
OUT PROGRAMMABLE PRO	OTECTION					
VBUS OVLO Range		Shutdown	4		24	V
Internal Overvoltage Trip Level	V <sub>OVLO_R</sub>	VBUS rising	-2	Progra mmable	+2	%
Internal Overvoltage Trip Hysteresis	V <sub>OVLO_F</sub>	VBUS falling		0.2		%
		4V – 8V [63]		63.5		
VBUS OVLO Resolution		8V – 16V [63]		127		mV
		12V – 24V [63]		190.5		

## **Electrical Characteristics (continued)**

 $(V_{BUS} = 2.7V \text{ to } 36V, V_{CC} = 2.6V \text{ to } 5.5V, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = 3.3V, T_A = +25^{\circ}\text{C})$  (Note 2)

PARAMETER	SYMBOL	CONE	MIN	TYP	MAX	UNITS	
V <sub>CC</sub>	•						
V <sub>CC</sub> Voltage Range	V <sub>CC</sub>			2.6	3.3	5.5	V
V <sub>CC</sub> Supply Current	l <sub>vcc</sub>	$V_{CC}$ = 4.2V, manual ( $I_{SRC}$ = 0mA)		125	200	μA	
V <sub>CC</sub> Shutdown Current		V <sub>CC</sub> = 4.2V, VBUS 1	floating, ENb = 1		2.8	5	μA
GATE							
		CATE external		m	in (VBUS, 5	SV)	
Maximum Gate On Voltage	$V_{GON}$	GATE external leakage <1µA	VBUS = 2.75V	2.43			V
			VBUS = 5V, 23V	4.6	-	5.4	
Gate Off	V <sub>GOFF</sub>					0.5	V
Soft-Start Comparator	V <sub>SS_THR</sub>			220	300	380	mV
ID CURRENT SOURCE							
Current Source Accuracy				-5		+5	%
Current Source Open Voltage	V <sub>OVSO</sub>	I <sub>ID</sub> = 2μΑ				2	V
					2		
Current Source					6		
					18		1
	I <sub>ID</sub>				54		μA
					162		1
					2500		
Average Current Source	I <sub>ID_AVG</sub>	162µA max current ISRC_MAN = 0	:, IS_PERIOD ≥ 130x,			2	μΑ
ADC	1	1					
Resolution					8		bit
Voltage step					5.9		mV
Full-Scale Error				-2		+2	%
Noise Filtering					100		μs
Full Scale					1.5		V
DIGITAL SIGNALS (SDA, SO	CL, INT)	•					1
Output Low Voltage	V <sub>OL</sub>	V <sub>IO</sub> = 3.3V, I <sub>SINK</sub> =	: 3mA			0.4	V
Leakage Current		V <sub>IO</sub> = 2.6V, open-d				1	μA
Input Logic-High	V <sub>IH</sub>			1.3			V
Input Logic-Low	V <sub>IL</sub>					0.4	V
Input Leakage Current	I <sub>BUS_LEAK</sub>	V <sub>IN</sub> = 0V, V <sub>IN</sub> = 2.6	SV .	-1		+1	μA

### **Electrical Characteristics (continued)**

 $(V_{BUS} = 2.7V \text{ to } 36V, V_{CC} = 2.6V \text{ to } 5.5V, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = 3.3V, T_A = +25^{\circ}\text{C}$ ) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS				
TIMING CHARACTERISTICS										
VBUS Debounce Time	t <sub>DEB</sub>	VBUS = 4.3V to charge pump on (OUT = 10% of VBUS), $R_{LOAD}$ = 100Ω, $C_{LOAD}$ = 10μF		Progra mmable		ms				
VBUS Soft-Start Time	t <sub>SS</sub>	IGATE = 4μA (typ)		50		ms				
VBUS Fast OVP Turn Off Response Time	tOFF	From VBUS > V <sub>OVLO_R</sub> to V <sub>GATE_TO_SOURCE</sub> = 0.5V, C <sub>GATE_TO_OUT</sub> = 4nF		100		ns				
Programmable Time Accuracy			-10		+10	%				
I <sup>2</sup> C Maximum Clock Frequency				400		kHz				
THERMAL PROTECTION										
Thermal Shutdown				125		°C				
Thermal Shutdown Hysteresis				20		°C				

**Note 2:** All devices are 100% production tested at T<sub>A</sub> = +25°C. Specifications over the operating temperature range are guaranteed by design.

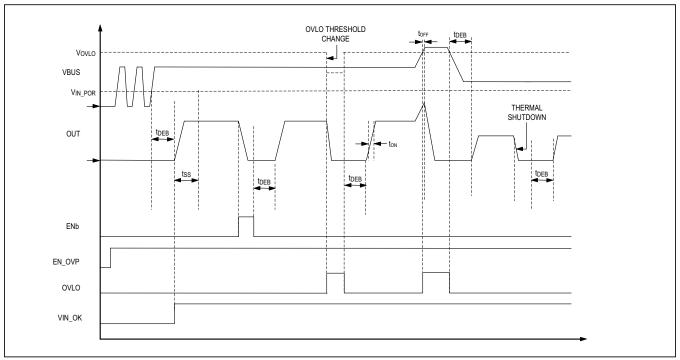
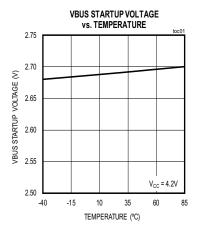
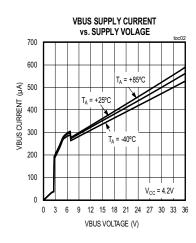


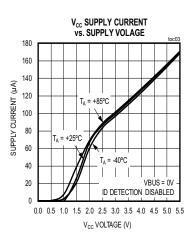
Figure 1. Timing Diagram

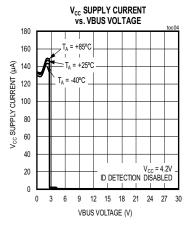
### **Typical Operating Characteristics**

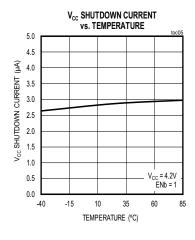
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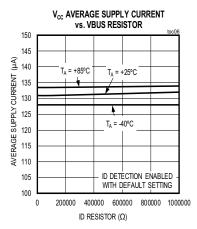


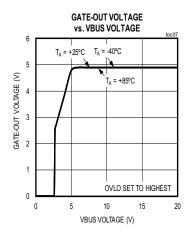


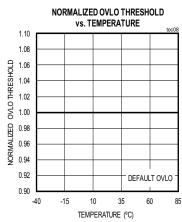


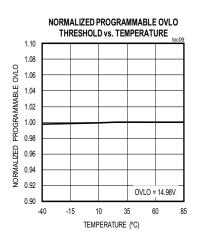






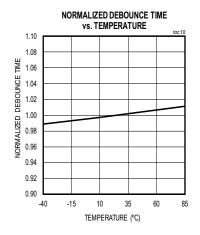


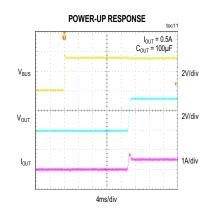


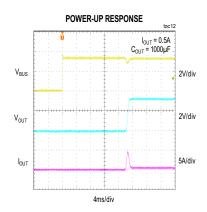


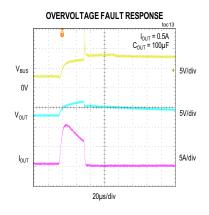
## **Typical Operating Characteristics (continued)**

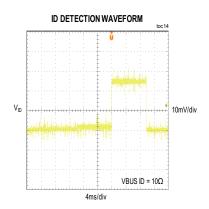
( $V_{CC}$  = 4.2V,  $T_A$  = +25°C, unless otherwise noted.)

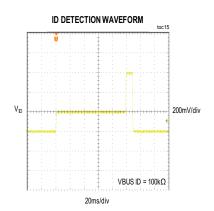




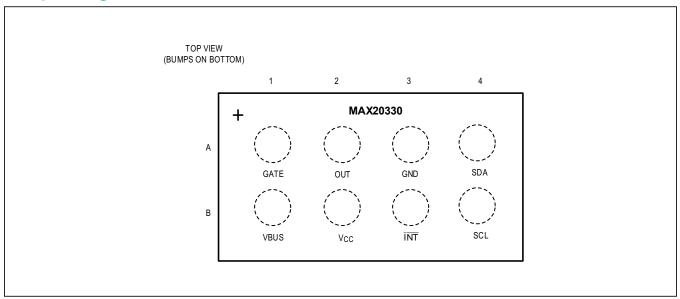








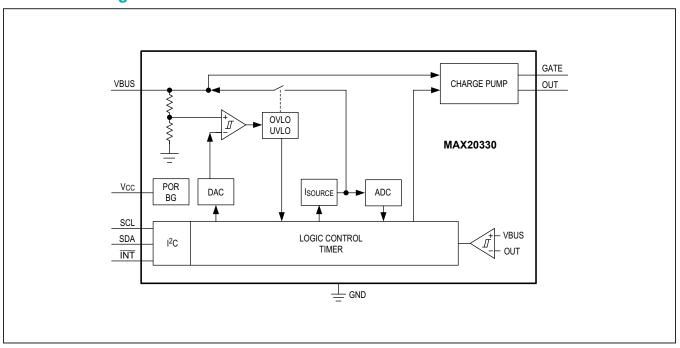
## **Bump Configuration**



## **Bump Description**

BUMP	NAME	FUNCTION
A1	GATE	Gate Drive Output for External N-FET
A2	OUT	Output Voltage to the Battery Terminal. Output of internal switch.
А3	GND	Ground
A4	SDA	I <sup>2</sup> C Data Line. Connect SDA to an external pullup resistor.
B1	VBUS	VBUS Input. For proper ESD and surge protection, place the external TVS and a 0.1µF capacitor on VBUS.
B2	V <sub>CC</sub>	Supply for the $I^2C$ Digital Block. Bypass $V_{CC}$ to ground with a $0.1\mu F$ capacitor as close to the device as possible.
В3	ĪNT	Interrupt Output.
B4	SCL	I <sup>2</sup> C Clock. Connect SCL to an external pullup resistor.

## **Functional Diagram**



**Table 1. Register Map** 

ADDRESS	NAME	TYPE	DEFAULT	DESCRIPTION
0x00	CHIP ID	Read Only	0x00	Device ID Register
0x01	CONTROL 1	RW	0x88	System Control 1
0x02	STATUS	Read Only	0x00	Status Register
0x03	INTERRUPT	Clear on Read	0x00	Interrupt Register
0x04	MASK	RW	0xFF	Mask Register
0x05	SET_OVLO	RW	0x2C	OVLO Threshold
0x06	I_SRC	RW	0x01	Current Source Threshold
0x07	I_SRC_TMR	RW	0x1B	Current Source On-Timer
0x08	CONTROL 2	RW	0x3C	System Control 2
0x0A	ACCDET_REF	RW	0xF0	Accessory Detection Threshold
0x0B	ISRC_ADC	Read Only	0x00	Current Source Output
0x0C	VBUS_ADC	Read Only	0x00	Current Source Output

## **Table 2. Detailed Register Map**

CHIP ID 0X00 (READ ON	LY)				,				
BIT	7	6	5	4	3	2	1	0	
BIT NAME		CHIP_ID CHIP_REV							
Reset Value	0	0	0	0	0	0	0	0	
Description	Chip ID and	Revision							
CONTROL 1 0x01 (Read/V	Vrite)								
BIT	7	6	5	4	3	2	1	0	
BIT NAME	EN_OVP	EN_IS	RFU	VBUS	S_DET	VBUSADC _EN	RFU	ENb	
Reset Value MAX20330	1	0	0	0	1	0	0	0	
Reset Value MAX20330B	0	0	0	0	1	0	0	0	
EN_OVP	0 = OVP dis	sabled (MAX2	ind EN_IS cai 20330B defau 20330 default)	lt)	it the same t	ime)			
EN_IS		irce (I_SRC) disabled (defa enabled							
RFU	Reserved for	r future use							
VBUS_DET		ounce Time (t min time for default)							
VBUSADC_EN	one time AD	One Time ADC for VBUS. The bit is cleared after the measurement. EN_OVP = 1 is required to run one time ADC for VBUS.  0 = VBUS ADC is disabled  1 = VBUS ADC is enabled							
ENb	0 = device is	ve Low Enab s in active mo s in sleep mo	, ,	BUS rising e	dge.				

**Table 2. Detailed Register Map (continued)** 

STATUS 0x02 (Read Only	)							
BIT	7	6	5	4	3	2	1	0
BIT NAME	VIN_OK	RFU	EOC	TP_OUT	ACC_ DET	THERM_ SHDN	OUT_ SHRT	OVLO
Reset Value	0	0	0	0	0	0	0	0
VIN_OK	0 = VBUS is	is above 2.7 below 2.7V above 2.7V	(typ)					
RFU	Reserved for	r future use						
EOC	0 = no conv	Conversion ersion since C data since						
TP_OUT	Timer Period 0 = timer period 1 = timer period	riod not expi	red					
ACC_DET	Accessory [ 0 = no chan 1 = accesso		tus					
THERM_SHDN	Thermal Sh 0 = no therm 1 = thermal	nal shutdown						
OUT_SHRT	OUT does not reach 90% of VBUS within Soft Start Time 0 = OUT ok 1 = OUT not ok							
OVLO	Overvoltage Shutdown 0 = no OVP shutdown 1 = OVP shutdown							

## **Table 2. Detailed Register Map (continued)**

INTERRUPT 0x03 (CI	ear on Read)							
BIT	7	6	5	4	3	2	1	0
BIT NAME	VIN_OKi	RFU	EOCi	TP_OUTi	ACC_ DETi	THERM_ SHDNi	OUT_ SHRTi	OVLOi
Reset Value	0	0	0	0	0	0	0	0
VIN_OKi	VIN (VBUS) 0 = interrupt 1 = interrupt	not occurre	V (typ) interi	-upt				
RFU	Reserved fo	r future use						
EOCi	ADC EOC ir 0 = interrupt 1 = interrupt	not occurre	d					
TP_OUTi	Timer Period 0 = interrupt 1 = interrupt	not occurre						
ACC_DETi	Accessory D 0 = interrupt 1 = interrupt	not occurre						
THERM_SHDNi	Thermal Sho 0 = interrupt 1 = interrupt	not occurre						
OUT_SHRTi	0 = interrupt	OUT does not reach 90% of VBUS within soft-start time interrupt 0 = interrupt not occurred 1 = interrupt occurred						
OVLOi	0 = interrupt	Overvoltage shutdown interrupt 0 = interrupt not occurred 1 = interrupt occurred						

**Table 2. Detailed Register Map (continued)** 

MASK 0x04 (Read/Wr	ite)									
BIT	7	6	5	4	3	2	1	0		
BIT NAME	VIN_OKm	RFU	EOCm	TP_ OUTm	ACC_ DETm	THERM_ SHDNm	OUT_ SHRTm	OVLOm		
Reset Value	1	1	1	1	1	1	1	1		
VIN_OKm	, , ,	VIN (VBUS) is above 2.7V (typ) interrupt 0 = not masked 1 = masked								
RFU	Reserved for	future use								
EOCm	ADC EOC in 0 = not mask 1 = masked									
TP_OUTm	Timer Period 0 = not mask 1 = masked		upt							
ACC_DETm	Accessory D 0 = not mask 1 = masked		errupt							
THERM_SHDNm	Thermal Shu 0 = not mask 1 = masked		rupt							
OUT_SHRTm	OUT does no 0 = not mask 1 = masked		% of VBUS wi	thin soft start	time interrup	t				
OVLOm	Overvoltage 0 = not mask 1 = masked		nterrupt							
SET_OVLO 0x05 (Rea	d/Write)									
BIT	7	6	5	4	3	2	1	0		
BIT NAME				SET_	OVLO					
Reset Value	0	0	1	0	1	1	0	0		
SET_OVLO	0000,0000 - 0100,0000 - 1000,0000 - 1100,0000 -	OVLO Threshold Set (8 bit resolution) 0000,0000 – 0011, 1111: 4V-8V [63 steps] (1.59% resolution) 0100,0000 – 0111,1111: 8V-16V [63 steps] 1000,0000 – 1011,1111: 12V-24V [63 steps] 1100,0000 – 1111,1111: 12V-24V [63 steps] Default: 6.8V								

**Table 2. Detailed Register Map (continued)** 

I_SRC 0x06 (Read/W	/rite)			r								
BIT	7	6	5	4	3	2	1	0				
BIT NAME	RFU	RFU I_SRC_MON RFU I_SRC_SET										
Reset Value	0	0	0	0	0	0	0	1				
RFU	Reserved for future use.											
I_SRC_MON (Read Only)	110 = 2500µ	$000 = off$ $001 = 2\mu A$ $010 = 6\mu A$ $011 = 18\mu A$										
I_SRC_SET		e, it is the rode, it is the refault)	naximum curre ne fixed current			alue, the au	uto ID detection	is skipped.				
I_SRC_TMR 0x07 (R	ead/Write)											
BIT	7	6	5	4	3	2	1	0				
BIT NAME	RF	J	IS_PE	RIOD	IS_INIT_SET		IS_TDET					
Reset Value	0	0	0	1	1	0	1	1				
RFU	Reserved for	future use	Э.									
IS_PERIOD	Repeat period 00 = 4x 01 = 130x (d 10 = 250x 11 = 1600x		od									
IS_INIT_SET	0 = use IS_PI 1 = use IS_PI	ERIOD and ERIOD = 00	IS_TDET for th O and IS_TDET	e initial chec = 101 as the	k (2µA) e initial value. If th	ne current so	ction auto-mode ource needs to in a larger than 2µA	crease,				
IS_TDET	Current sour 000 = 2500µ 001 = 3500µ 010 = 4000µ 011 = 10000 100 = 40000 101 = 10000 110 = 40000 111 = 1sec	s s s us (default µs 0µs	for detection									

**Table 2. Detailed Register Map (continued)** 

CONTROL2 0x08 (Read	d/Write)							
BIT	7	6	5	4	3	2	1	0
BIT NAME	RFU	EN_ VBPD	VBPD	_TMR	AUT_IS	RC_SCL	ISRC_ MAN	ISRC_ST
Reset Value	0	0	1	1	1	1	0	0
RFU	Reserved for	Reserved for future use.						
EN_VBPD	0 = pull dov	$1k\Omega$ VBUS pulldown enable bit. The bit is cleared after pull down time expires. 0 = pull down disabled (default) 1 = pull down enabled						
VBPD_TMR	00 = 5ms 01 = 15ms 10 = 30ms	01 = 15ms						
AUT_ISRC_SCL	00 = 10% o 01 = 20% o 10 = 30% o	Automatic scaling for impedance detection reference 00 = 10% of full ADC scale 01 = 20% of full ADC scale 10 = 30% of full ADC scale 11 = 30% of full ADC scale (default)						
ISRC_MAN	0 = automa 1 = manual	Current source manual detection 0 = automatic scaling for detection when ENb = 0 (default) 1 = manual detection when ENb = 0, fixed based on I_SRC and ISRC_TMR register values (register 0x06 and 0x07)						
ISRC_ST	0 = disable	Current source manual start and ADC conversion. The bit is cleared after one impedance detection.  0 = disable (default)  1 = start one manual impedance detection						
ACCDET_REF 0x0A (R	ead/Write)							
BIT	7	6	5	4	3	2	1	0
BIT NAME				ACC_D	ET_TH			
Reset Value	1	1	1	1	0	0	0	0
ACC_DET_TH		Accessory Detection Threshold Accessory is detected (ACC_DET = 1) if ADC_1 (0x0B) final reading is lower than ACC_DET_TH						

**Table 2. Detailed Register Map (continued)** 

ISRC_ADC 0x0B (Read Only)								
BIT	7	6	5	4	3	2	1	0
BIT NAME	ADC_1							
Reset Value	0	0	0	0	0	0	0	0
ADC_1	ID ADC: 0V to 1.5V Voltage step 5.9mV (typ)							
VBUS_ADC 0x0C (Read Only)							_	
BIT	7	6	5	4	3	2	1	0
BIT NAME	ADC_2							
Reset Value	0	0	0	0	0	0	0	0
ADC_2	VBUS ADC: 3V to 30V Voltage step 118mV (typ) Write 1 to VBUSADC_EN for one time VBUS ADC							

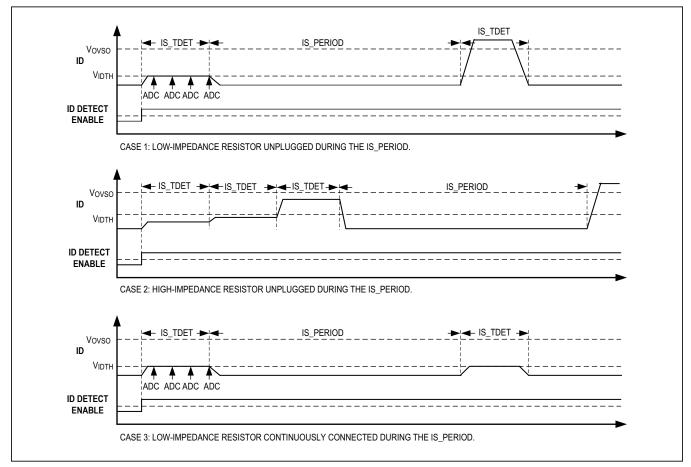


Figure 2. Current Source On-Time Timing Diagram (IS\_INIT\_SET = 0)

#### **Detailed Description**

The MAX20330 features the overvoltage protection to the charger input VBUS line when a travel adapter (TA) is used. The MAX20330 uses the external N-MOSFET with  $R_{ON}$  lower than  $10m\Omega$  and  $V_{DS}$  rating at or higher than +30V. The device protects the battery and low voltage systems against voltage faults up to  $40V_{DC}.$  The external TVS could be used to further protect the device from surges. If the input voltage exceeds the overvoltage threshold, the external N-FET is disconnected from the input to prevent damage to the protected components. In addition to the OVP controller function, the MAX20330 also provides the accessory ID detection as well as VBUS short detection when the device is not in OVP mode (EN\_OVP = 0).

#### **ENb Bit**

The MAX20330 is enabled by default. When disabled as VBUS is available, the part will remain enabled sinking current from VBUS.

#### 36VDC (40V Abs Max) Withstanding

The MAX20330 can withstand the DC voltage up to 40V. If 40V input is expected, it is recommended to use the external TVS that clamps the surge to 40V or below.

#### **OVLO**

OUT is connected to VBUS when VBUS is between UVLO threshold and OVLO threshold. When VBUS goes above overvoltage lockout threshold (SET\_OVLO 0x05), OUT is disconnected from VBUS, the OVLO bit is set high. When VBUS drops below SET\_OVLO threshold, the OVLO bit is deasserted and the debounce time starts counting. After the debounce time, OUT follows VBUS again.

#### **UVLO/POR**

The VBUS has min operating voltage of 2.7V. The ADC works when  $V_{CC}$  voltage is 2.6V or higher. The device disables the external FET unless VBUS is higher than UVLO threshold. When the device is operating with I<sup>2</sup>C ENb bit = 0 (default), if the UVLO happens, the device shuts down the switch immediately.

#### Safe Turn-On Protection

When the switch turns on, if the OUT is below V<sub>SS\_THR</sub> of VBUS after soft start time out, it shuts down the output.

#### **Fast Turn-Off Time**

The MAX20330 provides 100ns turn off response time and can switch off an external N-MOSFET.

#### **VBUS ID/Short Detection**

The MAX20330 can check the VBUS impedance with automatic scaling for the best resolution using the different current resources. The current source can be turned on only when the OVP function is disabled (EN\_OVP = 0). The ID open load voltage is 2V max. When the VBUS is soft shorted to ground, it can be detected and warn the user. Also, VBUS can be actively discharged by I<sup>2</sup>C command. This is useful when the OVP IC blocks the VBUS from discharged by the PMIC or by the USB type C controller during power down operation.

#### **Thermal Shutdown**

Thermal shutdown circuitry protects the devices from overheating. The switches turn off when the junction temperature exceeds +125°C (typ). The switches turn on again after the device temperature drops by approximately 20°C (typ).

### **Application Information**

#### I<sup>2</sup>C Interface

When in I<sup>2</sup>C mode, the MAX20330 operates as a slave device that sends and receives data through an I<sup>2</sup>C-compatible 2-wire interface. The interface uses a serial data line (SDA) and a serial clock line (SCL) to achieve bidirectional communication between master(s) and slave(s). A master (typically a microcontroller) initiates all data transfers to and from the MAX20330 and generates the SCL clock that synchronizes the data transfer. The SDA line operates as both an input and an open-drain output. A pullup resistor is required on SDA. The SCL line operates only as an input. A pullup resistor is required on SCL if there are multiple masters on the 2-wire interface, or

if the master in a single-master system has an open-drain SCL output. Each transmission consists of a START condition sent by a master, followed by the MAX20330 7-bit slave address plus R/W bit, a register address byte, one or more data bytes, and finally a STOP condition (Figure 3).

#### **Start and Stop Conditions**

Both SCL and SDA remain high when the interface is not busy. A master signals the beginning of a transmission with a START (S) condition by transitioning SDA from high-to-low while SCL is high (Figure 4). When the master has finished communicating with the slave, it issues a STOP (P) condition by transitioning SDA from low to high while SCL is high. The bus is then free for another transmission.

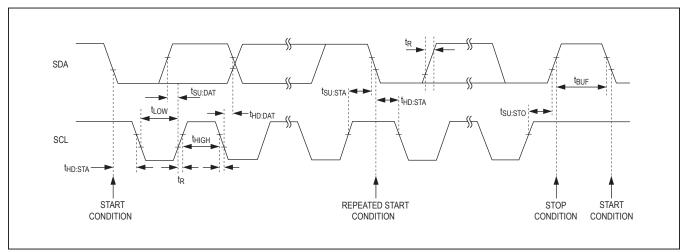


Figure 3. I<sup>2</sup>C Interface Timing Details

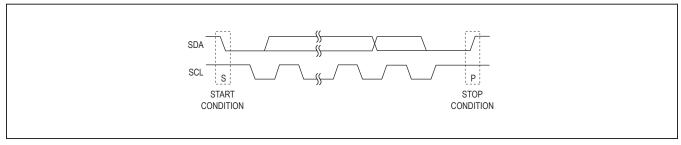


Figure 4. Start and Stop Conditions

#### **Bit Transfer**

One data bit is transferred during each clock pulse (Figure 5). The data on SDA must remain stable while SCL is high. Changes in SDA while SCK is high and stable are considered control signals (see *Start and Stop Conditions*)

#### **Acknowledge**

The acknowledge bit is a clocked 9<sup>th</sup> bit (<u>Figure 6</u>), which the recipient uses to handshake receipt of each byte of data. Thus, each byte transferred effectively requires 9 bits. The master generates the 9<sup>th</sup> clock pulse, and the recipient pulls down SDA during the acknowledge clock pulse. The SDA line is stable low during the high period of the clock pulse. When the master is transmitting to the MAX20330, it generates the acknowledge bit because the

device is the recipient. When the device is transmitting to the master, the master generates the acknowledge bit because the master is the recipient. If the device did not pull SDA low, a not acknowledge is indicated.

#### **Slave Address**

The MAX20330 features a 7-bit slave address: 0010 111. The bit following a 7-bit slave address is the  $R/\overline{W}$  bit, which is low for a write command and high for a read command.

#### **Bus Reset**

The MAX20330 resets the bus with the I<sup>2</sup>C start condition for reads. When the  $R/\overline{W}$  bit is set to 1, the device transmits data to the master, thus the master is reading from the device.

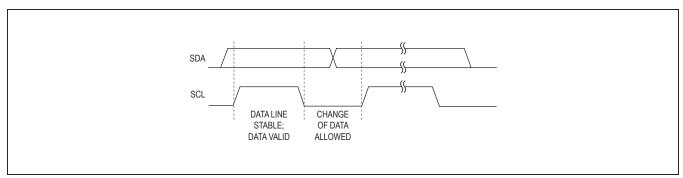


Figure 5. Bit Transfer

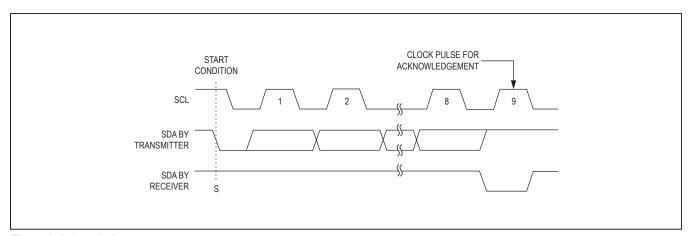


Figure 6. Acknowledge

#### **Format for Writing**

A write to the MAX20330 comprises the transmission of the slave address with the  $R/\overline{W}$  bit set to zero, followed by at least 1 byte of information. The first byte of information is the register address or command byte. The register address determines which register of the device is to be written by the next byte, if received. If a STOP (P) condition is detected after the register address is received,

then the device takes no further action beyond storing the register address. Any bytes received after the register address are data bytes. The first data byte goes into the register selected by the register address and subsequent data bytes go into subsequent registers (Figure 7). If multiple data bytes are transmitted before a STOP condition, these bytes are stored in subsequent registers because the register addresses autoincrement (Figure 8).

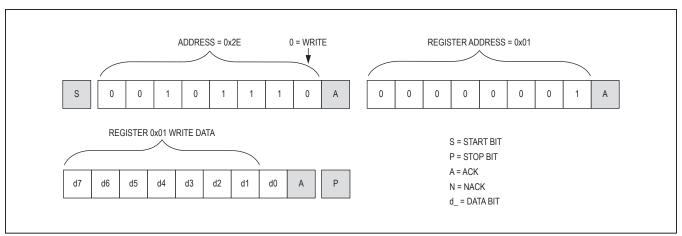


Figure 7. Format for I<sup>2</sup>C Write

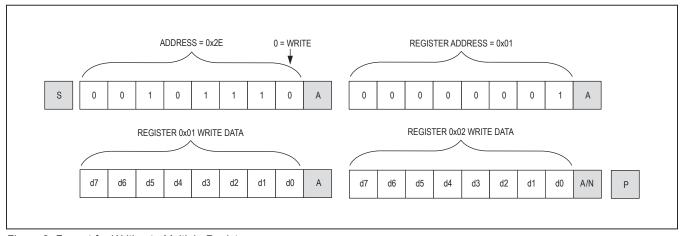


Figure 8. Format for Writing to Multiple Registers

#### Format for Reading

The MAX20330 is read using the internally stored register address as an address pointer, the same way the stored register address is used as an address pointer for a write. The pointer autoincrements after each data byte is read using the same rules as for a write. Thus, a read is initiated

by first configuring the register address by performing a write (Figure 9). The master can now read consecutive bytes from the device, with the first data byte being read from the register addressed pointed by the previously written register address (Figure 10). Once the master sounds a NACK, the MAX20330 stops sending valid data.

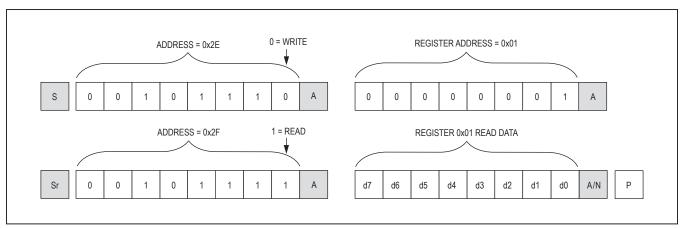


Figure 9. Format for Reads (Repeated Start)

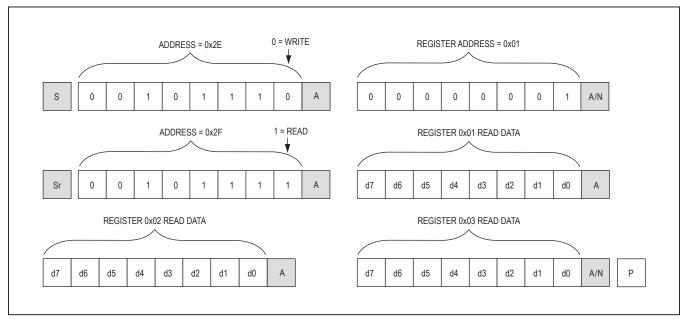
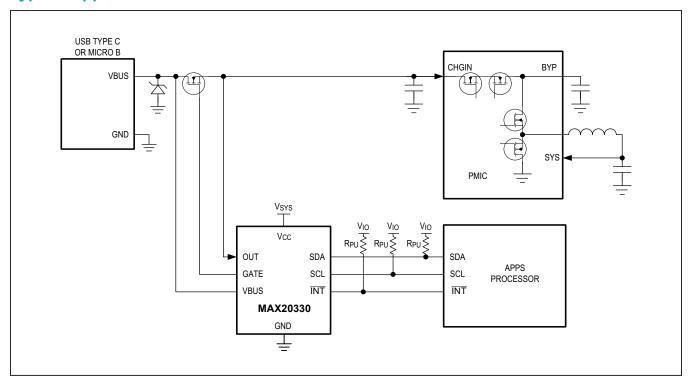
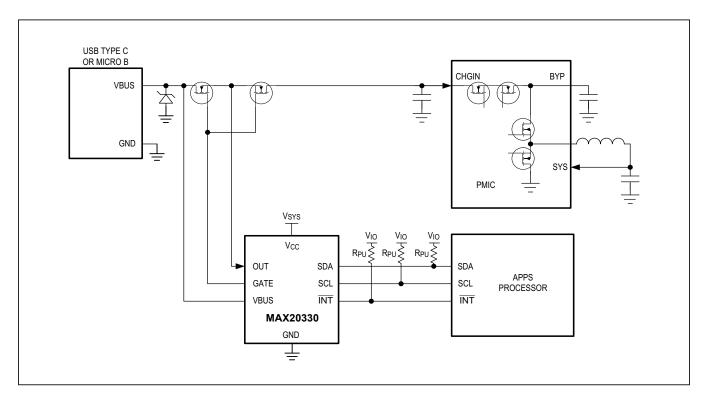


Figure 10. Format for Reading Multiple Registers

## **Typical Application Circuits**





## **Ordering Information**

PART	TOP MARK	TEMP RANGE	PIN- PACKAGE
MAX20330EWA+T	CA	-40°C TO +85°C	8 WLP
MAX20330BEWA+T	CC	-40°C TO +85°C	8 WLP

<sup>+</sup> Denotes lead(Pb)-free/RoHS-compliant package.

# Chip Information PROCESS: BiCMOS

Maxim Integrated | 22 www.maximintegrated.com

T = Tape and reel.